L Number	Hits	Search Text	DB	Time stamp
1	2	5117282.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 19:28
3	30	(interconnect adj substrate) and projected	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 19:35
4	173	(interconnect adj substrate) and projection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 19:43
5	47	(interconnect adj substrate) and folded	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:20
6	36	(interconnect adj substrate) and fold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 19:53
7	21	(interconnect adj substrate) and folding	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 19:54
8	11	(interconnect adj substrate) and superposed	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 19:55
9	127	(interconnect adj substrate) and bend	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 19:58
10	0	(interconnect adj substrate) and bended	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 19:58
11	110	(interconnect adj substrate) and bending	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:00
12	97	(interconnect adj substrate) and protruding	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:03
13	122	(interconnect adj substrate) and protrude	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:05
14	17	(interconnect adj substrate) and protruded	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:06
15	1	(interconnect adj substrate) and (positioning adj reference)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:07

16	7	(interconnect adj substrate) and (position adj reference)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:08
17	0	(interconnect adj substrate) and (end adj parts)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:08
18	38	(interconnect adj substrate) and (end adj points)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:10
19	1	(interconnect adj substrate) and (rectangular adj body)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:10
20	321	(interconnect adj substrate) and (rectangular)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:15
21	64	(interconnect adj substrate) and (rectangle)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:15
22	42	(interconnect adj pattern) and folded	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:21
23	41	(interconnect adj pattern) and fold	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:22
24	6	(interconnect adj pattern) and folding	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:35
25	172	(interconnect adj pattern) and projection	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:35
26	140	(interconnect adj pattern) and projecting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:35
27	122	(interconnect adj pattern) and projected	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:36
28	5	(interconnect adj pattern) and crease	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 20:55
29	244	folded adj substrate	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 21:21

30	2	5448511.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 21:21
31	2	5854507.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 21:23
32	390	257/771.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/09/01 21:24